

Title (en)

HYBRID CIRCUIT ARRANGEMENT WITH A THERMAL RELEASE

Title (de)

HYBRIDSCHALTUNGSANORDNUNG MIT THERMOSICHERUNG

Title (fr)

CONFIGURATION D'UN CIRCUIT HYBRIDE DOTE D'UN DECLENCHEUR THERMIQUE

Publication

**EP 1068626 A1 20010117 (DE)**

Application

**EP 99922032 A 19990316**

Priority

- DE 9900737 W 19990316
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Abstract (en)

[origin: DE19814445C1] According to the invention, a thermal release (6) is electrically connected to a resistance meander (1) and can be triggered by said meander (1) in the case of an overload when the circuit substrate (5) heats up. The resistance meander (1) is embodied in a defined area (4) on the circuit support as a multiple interlaced structure surrounding the hot spot (3) which is to be produced in an optimised manner and in a defined position. The thermal release is thermally coupled to the circuit substrate (5) at said hot spot (3).

IPC 1-7

**H01H 37/76**; **H01C 7/13**

IPC 8 full level

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